



Material Content Data Sheet



Sales Product Name	TLE7233G			Issued		4. July 2019		
MA#	MA005344680							
Package	PG-SSOP-24-5			Weight*		146.48 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.214	2.19	2.19	21942	21942
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		106	
	non noble metal	zinc	7440-66-6	0.062	0.04		425	
	non noble metal	iron	7439-89-6	1.245	0.85		8502	
	non noble metal	copper	7440-50-8	50.568	34.52	35.42	345225	354258
wire	noble metal	gold	7440-57-5	0.497	0.34	0.34	3395	3395
encapsulation	organic material	carbon black	1333-86-4	0.175	0.12		1193	
	plastics	epoxy resin	-	8.036	5.49		54860	
	inorganic material	silicondioxide	60676-86-0	79.136	54.03	59.64	540254	596307
leadfinish	non noble metal	tin	7440-31-5	1.680	1.15	1.15	11468	11468
plating	noble metal	silver	7440-22-4	0.365	0.25	0.25	2494	2494
glue	plastics	acrylic resin	-	0.327	0.22		2230	
	noble metal	silver	7440-22-4	1.158	0.79	1.01	7906	10136
*deviation	< 10%	Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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